

Product Change Notification



Microsemi Corporation
February 17, 2016

Product/Process Change Notification No: 1400A00241
Change Classification: Major Change

Subject: Die Shrink for 2GB and 4GB DDR3 SDRAM Products

Description of Change:

Microsemi Memory and Storage Solutions (MSS) would like to inform you that the following products will be affected as a result of a die shrink by the die vendor. Microsemi MSS is providing as much advance notice as possible of this major changes for these products. A subsequent PCN with new part numbers and the development/production release schedule will be issued by May 15, 2016. Please be assured that Microsemi MSS is fully committed to providing devices with the minimum Form, Fit and Function differences to the devices. Please contact your [Microsemi Sales Representative](#) for the current die availability and for questions/concerns you might have related to this change.

Reason for Change: Die Shrink

Application Impact: 4GB DDR3 Low Profile SDRAM and 2GB DDR3 SDRAM.

Products Affected by this Change: [W3J512M32GT-XB2X](#), [W3J512M32KT-XB2X](#), [W3J512M32G-XBX](#), [W3J512M32K-XBX](#), [W3J512M72G-XLBX](#), [W3J512M72K-XLBX](#), [W3J512M64G-XLBX](#), [W3J512M64K-XLBX](#).

Date of Engineering Samples Availability: TBD See Above

Qualification and Release to Production Date: TBD See Above

Production Shipment Schedule: TBD See Above

Last Time Buy Date for Current Product with Current Die: 01-30-2017

Last Time Ship Date for Current Product with Current Die: 01-30-2018

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Regards,

Microsemi Corporation